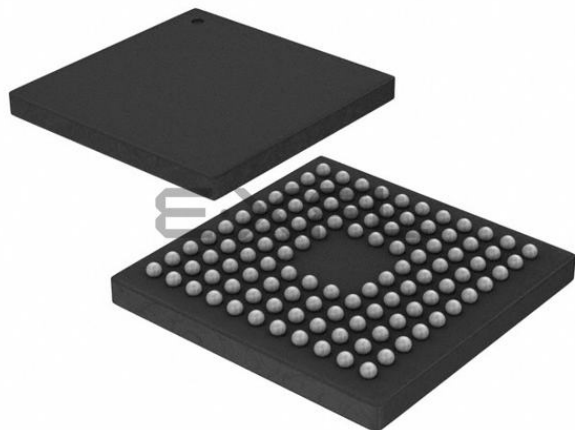




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Details

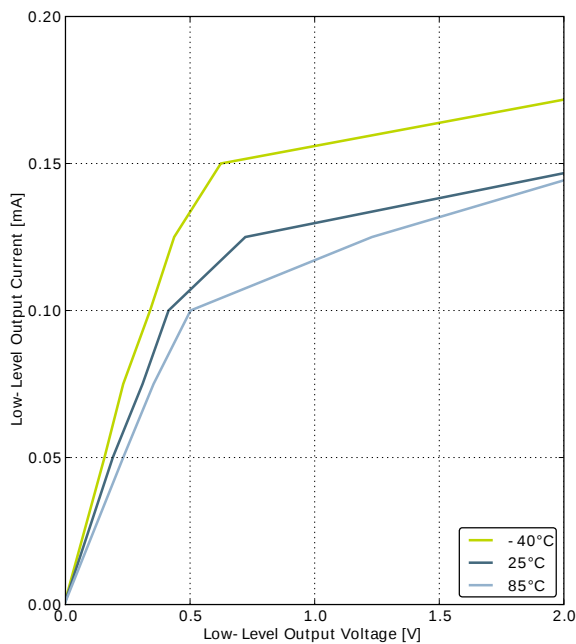
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	87
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LFBGA
Supplier Device Package	112-BGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg990f512g-e-bga112

Table 2.1. Configuration Summary

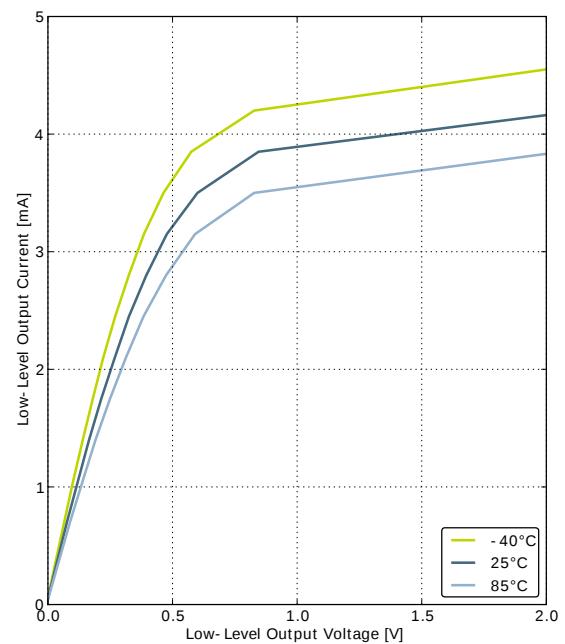
Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VBUS, USB_VBUSEN, USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP, USB_ID
EBI	Full configuration	EBI_A[27:0], EBI_AD[15:0], EBI_ARDY, EBI_ALE, EBI_BL[1:0], EBI_CS[3:0], EBI_CSTFT, EBI_DCLK, EBI_DTEN, EBI_HSNC, EBI_NANDREn, EBI_NANDWEn, EBI_REn, EBI_VSNC, EBI_WEn
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
UART0	Full configuration	U0_TX, U0_RX
UART1	Full configuration	U1_TX, U1_RX
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
TIMER3	Full configuration	TIM3_CC[2:0]
RTC	Full configuration	NA
BURTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O

Table 3.5. Power Management

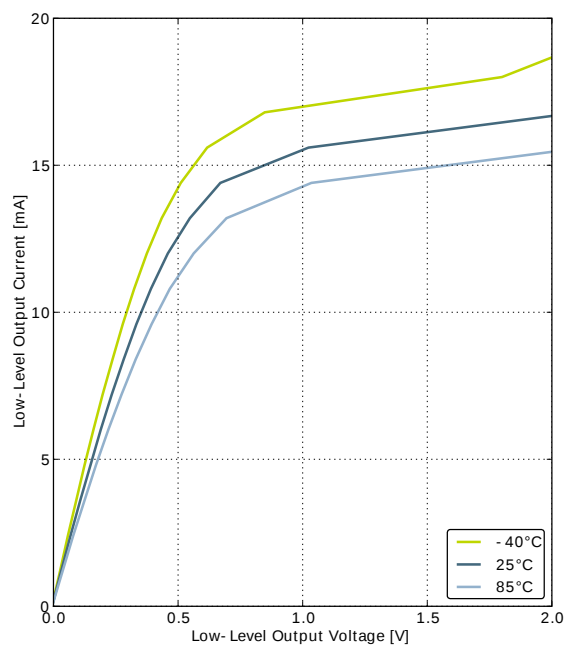
Symbol	Parameter	Condition	Min	Typ	Max	Unit
V _{BODextthr-}	BOD threshold on falling external supply voltage	EM0	1.74		1.96	V
		EM2	1.74		1.98	V
V _{BODintthr-}	BOD threshold on falling internally regulated supply voltage		1.57		1.70	V
V _{BODextthr+}	BOD threshold on rising external supply voltage			1.85	1.98	V
V _{PORthr+}	Power-on Reset (POR) threshold on rising external supply voltage				1.98	V
t _{RESET}	Delay from reset is released until program execution starts	Applies to Power-on Reset, Brown-out Reset and pin reset.		163		μs
C _{DECOUPLE}	Voltage regulator decoupling capacitor.	X5R capacitor recommended. Apply between DECOUPLE pin and GROUND		1		μF
C _{USB_VREGO}	USB voltage regulator out decoupling capacitor.	X5R capacitor recommended. Apply between USB_VREGO pin and GROUND		1		μF
C _{USB_VREGI}	USB voltage regulator in decoupling capacitor.	X5R capacitor recommended. Apply between USB_VREGI pin and GROUND		4.7		μF

Figure 3.4. Typical Low-Level Output Current, 2V Supply Voltage

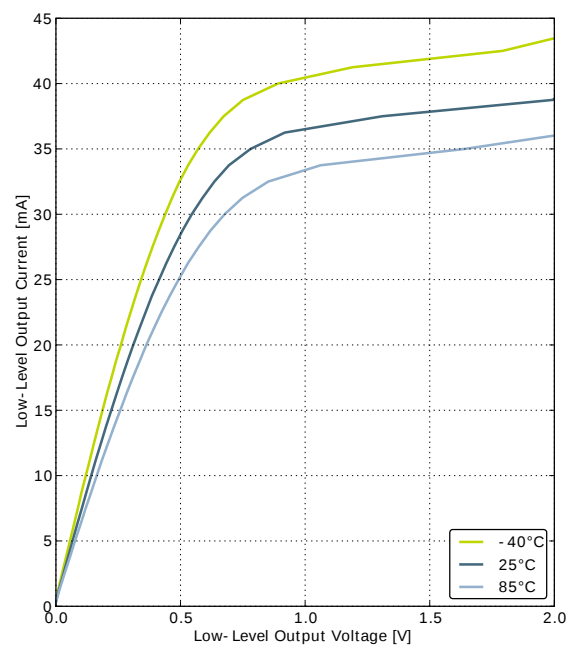
GPIO_Px_CTRL DRIVEMODE = LOWEST



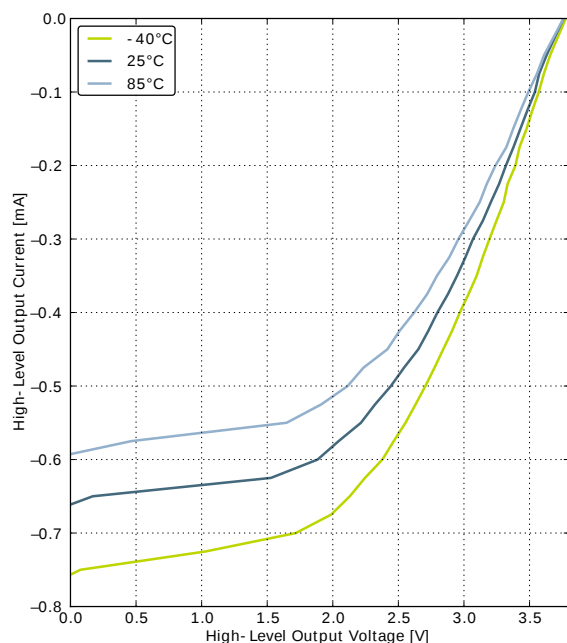
GPIO_Px_CTRL DRIVEMODE = LOW



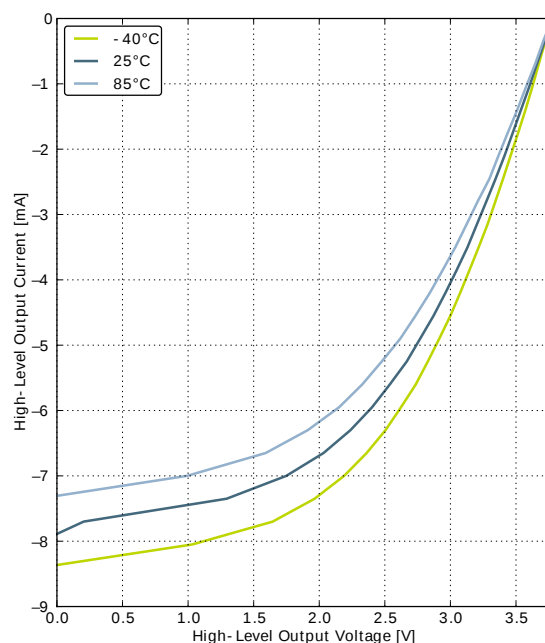
GPIO_Px_CTRL DRIVEMODE = STANDARD



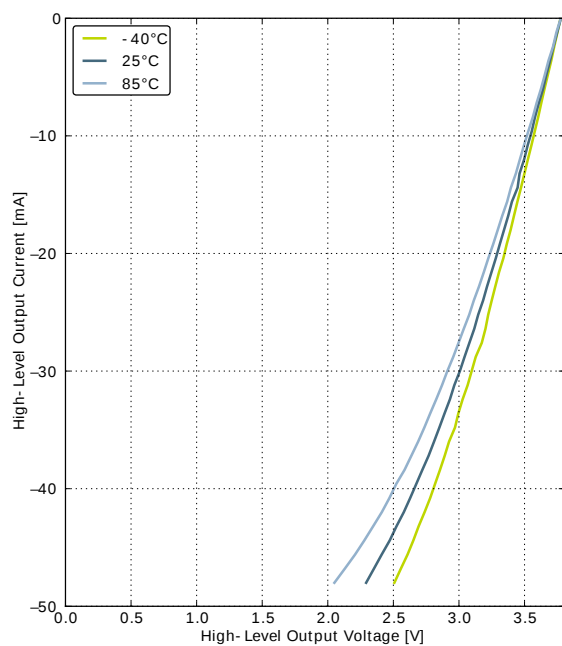
GPIO_Px_CTRL DRIVEMODE = HIGH

Figure 3.9. Typical High-Level Output Current, 3.8V Supply Voltage

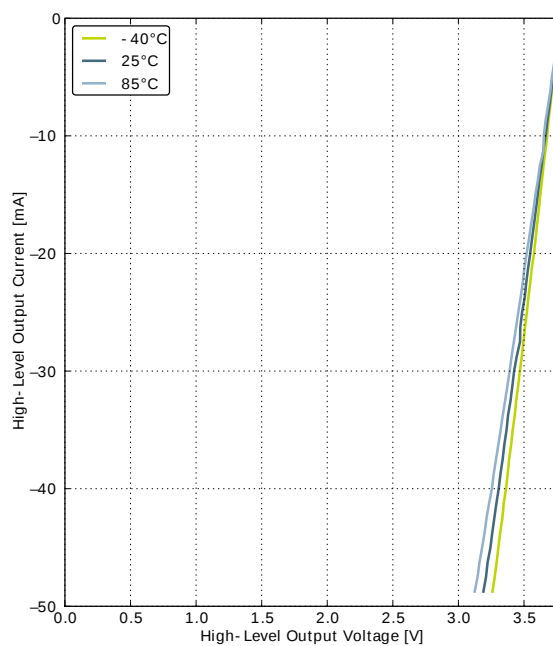
GPIO_Px_CTRL DRIVEMODE = LOWEST



GPIO_Px_CTRL DRIVEMODE = LOW



GPIO_Px_CTRL DRIVEMODE = STANDARD



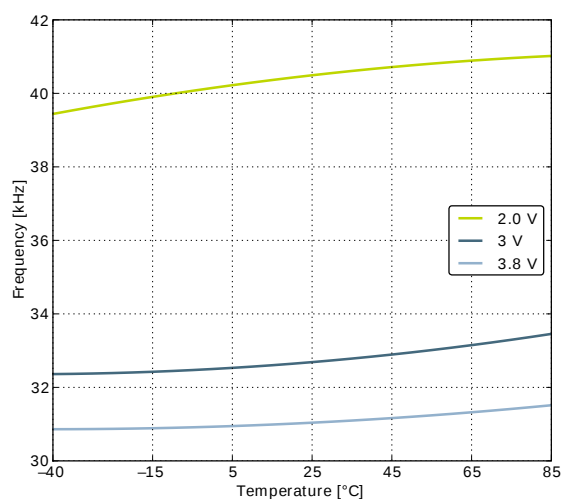
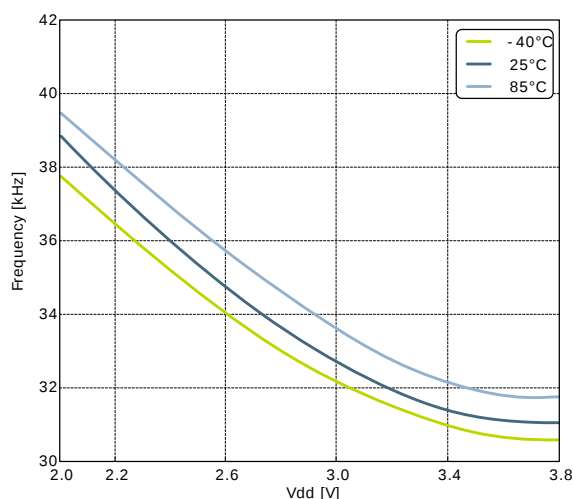
GPIO_Px_CTRL DRIVEMODE = HIGH

3.9.3 LFRCO

Table 3.10. LFRCO

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{LFRCO}	Oscillation frequency, $V_{\text{DD}} = 3.0 \text{ V}$, $T_{\text{AMB}} = 25^\circ\text{C}$		31.29	32.768	34.28	kHz
t_{LFRCO}	Startup time not including software calibration			150		μs
I_{LFRCO}	Current consumption			300	900	nA
$\text{TUNESTEP}_{\text{LFRCO}}$	Frequency step for LSB change in TUNING value			1.5		%

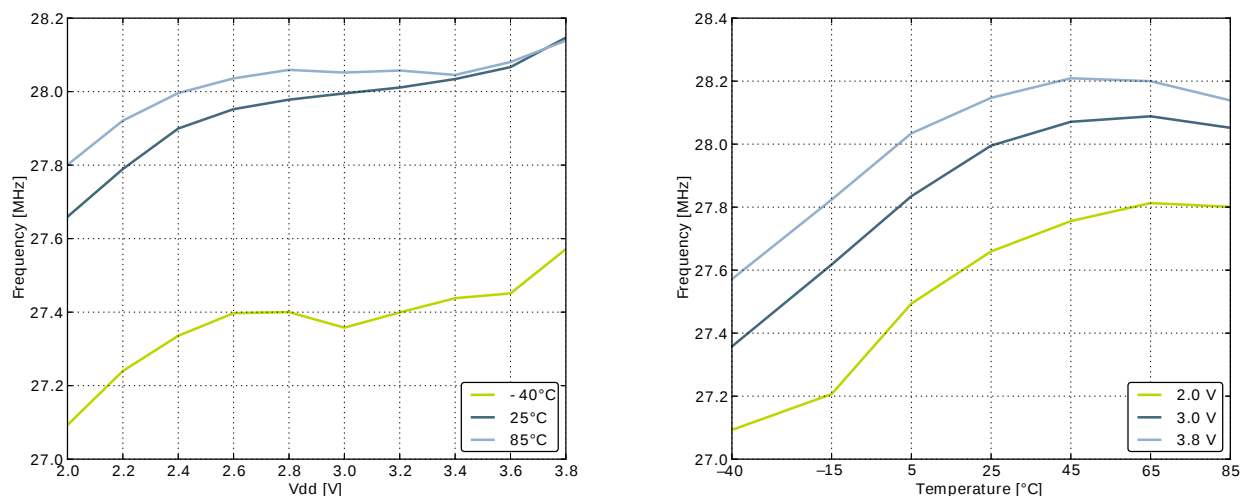
Figure 3.10. Calibrated LFRCO Frequency vs Temperature and Supply Voltage



3.9.4 HFRCO

Table 3.11. HFRCO

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{HFRCO}	Oscillation frequency, $V_{\text{DD}} = 3.0 \text{ V}$, $T_{\text{AMB}} = 25^\circ\text{C}$	28 MHz frequency band	27.5	28.0	28.5	MHz
		21 MHz frequency band	20.6	21.0	21.4	MHz
		14 MHz frequency band	13.7	14.0	14.3	MHz
		11 MHz frequency band	10.8	11.0	11.2	MHz
		7 MHz frequency band	6.48 ¹	6.60 ¹	6.72 ¹	MHz
		1 MHz frequency band	1.15 ²	1.20 ²	1.25 ²	MHz
$t_{\text{HFRCO_settling}}$	Settling time after start-up	$f_{\text{HFRCO}} = 14 \text{ MHz}$		0.6		Cycles
	Settling time after band switch			25		Cycles

Figure 3.16. Calibrated HFRCO 28 MHz Band Frequency vs Supply Voltage and Temperature

3.9.5 AUXHFRCO

Table 3.12. AUXHFRCO

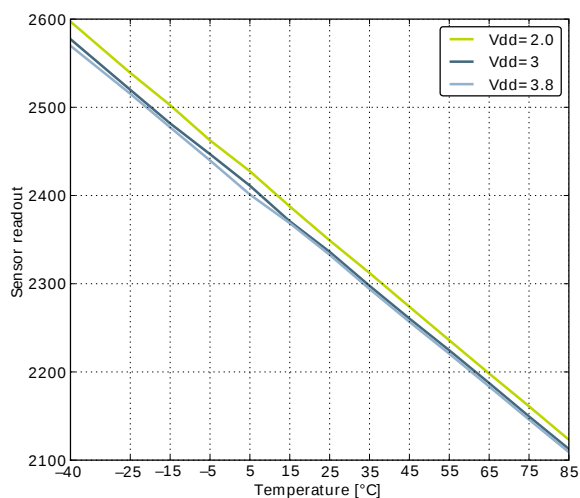
Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{AUXHFRCO}	Oscillation frequency, $V_{\text{DD}} = 3.0 \text{ V}$, $T_{\text{AMB}} = 25^\circ\text{C}$	28 MHz frequency band	27.5	28.0	28.5	MHz
		21 MHz frequency band	20.6	21.0	21.4	MHz
		14 MHz frequency band	13.7	14.0	14.3	MHz
		11 MHz frequency band	10.8	11.0	11.2	MHz
		7 MHz frequency band	6.48 ¹	6.60 ¹	6.72 ¹	MHz
		1 MHz frequency band	1.15 ²	1.20 ²	1.25 ²	MHz
$t_{\text{AUXHFRCO_settling}}$	Settling time after start-up	$f_{\text{AUXHFRCO}} = 14 \text{ MHz}$		0.6		Cycles
$\text{DC}_{\text{AUXHFRCO}}$	Duty cycle	$f_{\text{AUXHFRCO}} = 14 \text{ MHz}$	48.5	50	51	%
$\text{TUNESTEP}_{\text{AUXHFRCO}}$	Frequency step for LSB change in TUNING value			0.3 ³		%

¹For devices with prod. rev. < 19, Typ = 7MHz and Min/Max values not applicable.

²For devices with prod. rev. < 19, Typ = 1MHz and Min/Max values not applicable.

³The TUNING field in the CMU_AUXHFRCOCTRL register may be used to adjust the AUXHFRCO frequency. There is enough adjustment range to ensure that the frequency bands above 7 MHz will always have some overlap across supply voltage and temperature. By using a stable frequency reference such as the LFXO or HFXO, a firmware calibration routine can vary the TUNING bits and the frequency band to maintain the AUXHFRCO frequency at any arbitrary value between 7 MHz and 28 MHz across operating conditions.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
		200 kSamples/s, 12 bit, single ended, internal 1.25V reference		62		dB
		200 kSamples/s, 12 bit, single ended, internal 2.5V reference		63		dB
		200 kSamples/s, 12 bit, single ended, V_{DD} reference		67		dB
		200 kSamples/s, 12 bit, differential, internal 1.25V reference		63		dB
		200 kSamples/s, 12 bit, differential, internal 2.5V reference		66		dB
		200 kSamples/s, 12 bit, differential, 5V reference		66		dB
		200 kSamples/s, 12 bit, differential, V_{DD} reference	63	66		dB
		200 kSamples/s, 12 bit, differential, $2xV_{DD}$ reference		70		dB
SINAD _{ADC}	Signal-to-Noise And Distortion-ratio (SINAD)	1 MSamples/s, 12 bit, single ended, internal 1.25V reference		58		dB
		1 MSamples/s, 12 bit, single ended, internal 2.5V reference		62		dB
		1 MSamples/s, 12 bit, single ended, V_{DD} reference		64		dB
		1 MSamples/s, 12 bit, differential, internal 1.25V reference		60		dB
		1 MSamples/s, 12 bit, differential, internal 2.5V reference		64		dB
		1 MSamples/s, 12 bit, differential, 5V reference		54		dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference		66		dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference		68		dB
		200 kSamples/s, 12 bit, single ended, internal 1.25V reference		61		dB
		200 kSamples/s, 12 bit, single ended, internal 2.5V reference		65		dB
		200 kSamples/s, 12 bit, single ended, V_{DD} reference		66		dB
		200 kSamples/s, 12 bit, differential, internal 1.25V reference		63		dB
		200 kSamples/s, 12 bit, differential, internal 2.5V reference		66		dB
		200 kSamples/s, 12 bit, differential, 5V reference		66		dB
		200 kSamples/s, 12 bit, differential, V_{DD} reference	62	65		dB

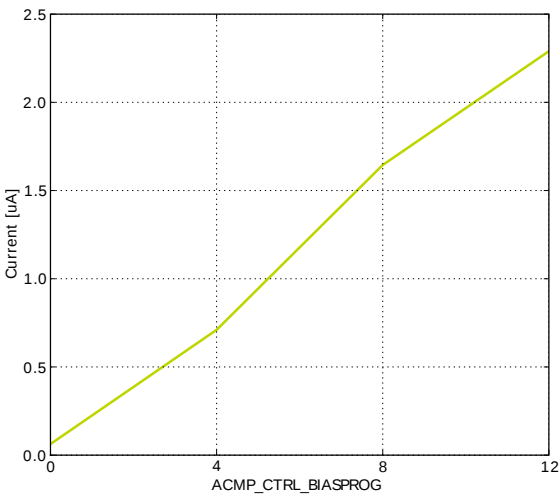
Figure 3.24. ADC Temperature sensor readout

3.11 Digital Analog Converter (DAC)

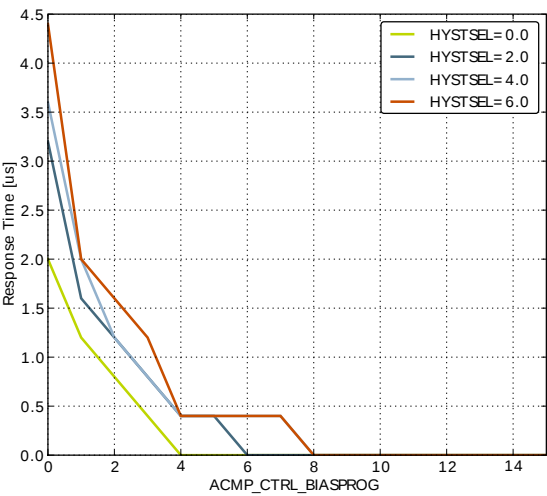
Table 3.15. DAC

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V_{DACOUT}	Output voltage range	VDD voltage reference, single ended	0		V_{DD}	V
		VDD voltage reference, differential	$-V_{DD}$		V_{DD}	V
V_{DACCM}	Output common mode voltage range		0		V_{DD}	V
I_{DAC}	Active current including references for 2 channels	500 kSamples/s, 12 bit		400 ¹	600 ¹	μA
		100 kSamples/s, 12 bit		200 ¹	260 ¹	μA
		1 kSamples/s 12 bit NORMAL		17 ¹	25 ¹	μA
SR_{DAC}	Sample rate				500	ksamples/s
f_{DAC}	DAC clock frequency	Continuous Mode			1000	kHz
		Sample/Hold Mode			250	kHz
		Sample/Off Mode			250	kHz
$CYC_{DACCONV}$	Clock cycles per conversion			2		
$t_{DACCONV}$	Conversion time		2			μs
$t_{DACSETTLE}$	Settling time			5		μs
SNR_{DAC}	Signal to Noise Ratio (SNR)	500 kSamples/s, 12 bit, single ended, internal 1.25V reference		58		dB
		500 kSamples/s, 12 bit, single ended, internal 2.5V reference		59		dB
		500 kSamples/s, 12 bit, differential, internal 1.25V reference		58		dB

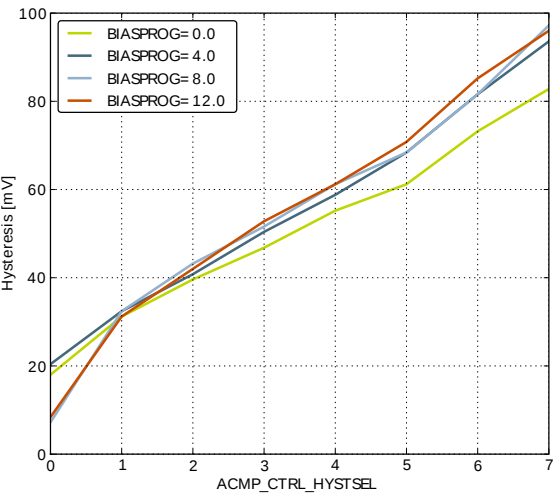
Figure 3.30. ACMP Characteristics, Vdd = 3V, Temp = 25°C, FULLBIAS = 0, HALFBIAS = 1



Current consumption, HYSTSEL = 4



Response time



Hysteresis

Table 3.19. EBI Write Enable Timing

Symbol	Parameter	Min	Typ	Max	Unit
$t_{OH_WEn}^{1\ 2\ 3\ 4}$	Output hold time, from trailing EBI_WEn/ EBI_NANDWEn edge to EBI_AD, EBI_A, EBI_CSn, EBI_BLn invalid	$-6.00 + (WRHOLD * t_{HFCORECLK})$			ns
$t_{OSU_WEn}^{1\ 2\ 3\ 4\ 5}$	Output setup time, from EBI_AD, EBI_A, EBI_CSn, EBI_BLn valid to leading EBI_WEn/ EBI_NANDWEn edge	$-14.00 + (WRSETUP * t_{HFCORECLK})$			ns
$t_{WIDTH_WEn}^{1\ 2\ 3\ 4\ 5}$	EBI_WEn/EBI_NANDWEn pulse width	$-7.00 + ((WRSTRB + 1) * t_{HFCORECLK})$			ns

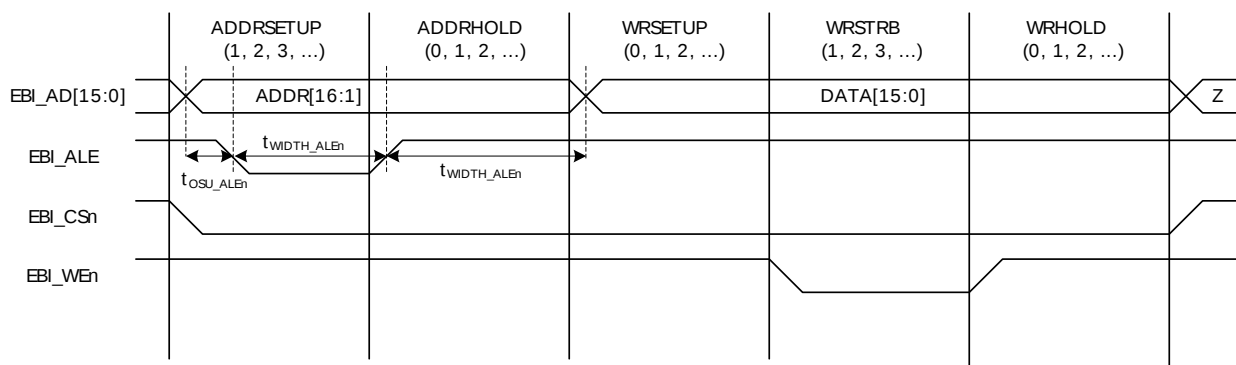
¹Applies for all addressing modes (figure only shows D16 addressing mode)

²Applies for both EBI_WEn and EBI_NANWEn (figure only shows EBI_WEn)

³Applies for all polarities (figure only shows active low signals)

⁴Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

⁵ The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFWE=0. The leading edge of EBI_WEn can be moved to the right by setting HALFWE=1. This decreases the length of t_{WIDTH_WEn} and increases the length of t_{OSU_WEn} by $1/2 * t_{HFCLKNODIV}$.

Figure 3.32. EBI Address Latch Enable Related Output Timing**Table 3.20. EBI Address Latch Enable Related Output Timing**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{OH_ALEn}^{1\ 2\ 3\ 4}$	Output hold time, from trailing EBI_ALE edge to EBI_AD invalid	$-6.00 + (ADDRHOLD^5 * t_{HFCORECLK})$			ns
$t_{OSU_ALEn}^{1\ 2\ 4}$	Output setup time, from EBI_AD valid to leading EBI_ALE edge	$-13.00 + (0 * t_{HFCORECLK})$			ns
$t_{WIDTH_ALEn}^{1\ 2\ 3\ 4}$	EBI_ALEn pulse width	$-7.00 + (ADDRSETUP + 1) * t_{HFCORECLK}$			ns

¹Applies to addressing modes D8A24ALE and D16A16ALE (figure only shows D16A16ALE)

²Applies for all polarities (figure only shows active low signals)

³ The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFALE=0. The trailing edge of EBI_ALE can be moved to the left by setting HALFALE=1. This decreases the length of t_{WIDTH_ALEn} and increases the length of t_{OH_ALEn} by $t_{HFCORECLK} - 1/2 * t_{HFCLKNODIV}$.

⁴Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

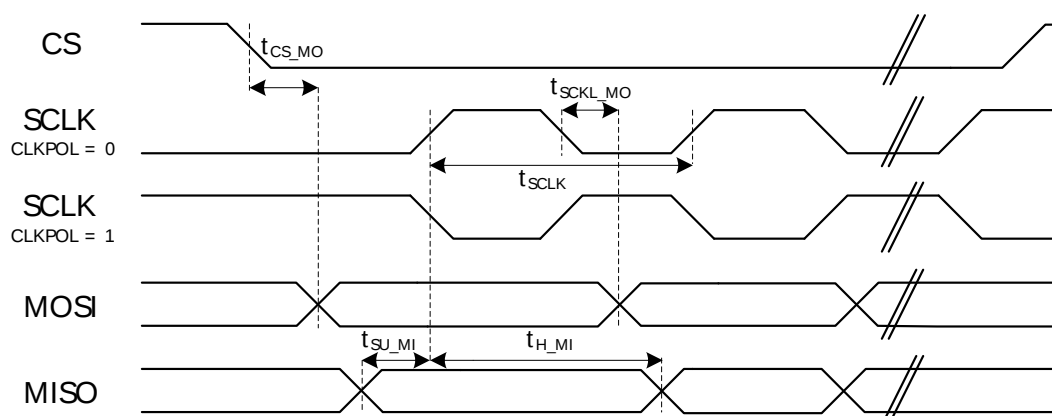
⁵Figure only shows a write operation. For a multiplexed read operation the address hold time is controlled via the RDSETUP state instead of via the ADDRHOLD state.

Table 3.27. I2C Fast-mode Plus (Fm+)

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL clock frequency	0		1000 ¹	kHz
t_{LOW}	SCL clock low time	0.5			μ s
t_{HIGH}	SCL clock high time	0.26			μ s
$t_{SU,DAT}$	SDA set-up time	50			ns
$t_{HD,DAT}$	SDA hold time	8			ns
$t_{SU,STA}$	Repeated START condition set-up time	0.26			μ s
$t_{HD,STA}$	(Repeated) START condition hold time	0.26			μ s
$t_{SU,STO}$	STOP condition set-up time	0.26			μ s
t_{BUF}	Bus free time between a STOP and START condition	0.5			μ s

¹For the minimum HPERCLK frequency required in Fast-mode Plus, see the I2C chapter in the EFM32GG Reference Manual.

3.18 USART SPI

Figure 3.36. SPI Master Timing**Table 3.28. SPI Master Timing**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{SCLK}^{1,2}$	SCLK period		$2 * t_{HFER-CLK}$			ns
$t_{CS_MO}^{1,2}$	CS to MOSI		-2.00		1.00	ns
$t_{SCLK_MO}^{1,2}$	SCLK to MOSI		-4.00		3.00	ns
$t_{SU_MI}^{1,2}$	MISO setup time	IOVDD = 1.98 V	36.00			ns
		IOVDD = 3.0 V	29.00			ns
$t_{H_MI}^{1,2}$	MISO hold time		-4.00			ns

¹Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)

²Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
					LEU1_RX #0	ETM_TD0 #2
H1	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
H2	PC2	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	EBI_A25 #0/1/2	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
H3	PD14				I2C0_SDA #3	
H4	PA7	LCD_SEG35	EBI_CSTFT #0/1/2			
H5	PA8	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
H6	VSS	Ground.				
H7	IOVDD_3	Digital IO power supply 3.				
H8	PD8	BU_VIN				CMU_CLK1 #1
H9	PD5	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2
H10	PD6	ADC0_CH6 OPAMP_P1		LETIM0_OUT0 #0 TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2 I2C0_SDA #1	LES_ALTEX0 #0 ACMP0_O #2 ETM_TD0 #0
H11	PD7	ADC0_CH7 OPAMP_N1		LETIM0_OUT1 #0 TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 #0 ACMP1_O #2 ETM_TCLK #0
J1	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
J2	PC3	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
J3	PD15				I2C0_SCL #3	
J4	PA12	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
J5	PA9	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
J6	PA10	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
J7	PB9		EBI_A03 #0/1/2		U1_TX #2	
J8	PB10		EBI_A04 #0/1/2		U1_RX #2	
J9	PD2	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	USB_DMPU #0 US1_CLK #1	DBG_SWO #3
J10	PD3	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2
J11	PD4	ADC0_CH4 OPAMP_P2			LEU0_TX #0	ETM_TD2 #0/2
K1	PB7	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
K2	PC4	ACMP0_CH4 OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
K3	PA13	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
K4	VSS	Ground.				
K5	PA11	LCD_SEG39	EBI_HSNC #0/1/2			
K6	RESETn	Reset input, active low.				

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
								Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.
EBI_A06	PC7	PC7	PC7					External Bus Interface (EBI) address output pin 06.
EBI_A07	PE0	PE0	PE0					External Bus Interface (EBI) address output pin 07.
EBI_A08	PE1	PE1	PE1					External Bus Interface (EBI) address output pin 08.
EBI_A09	PE2	PC9	PC9					External Bus Interface (EBI) address output pin 09.
EBI_A10	PE3	PC10	PC10					External Bus Interface (EBI) address output pin 10.
EBI_A11	PE4	PE4	PE4					External Bus Interface (EBI) address output pin 11.
EBI_A12	PE5	PE5	PE5					External Bus Interface (EBI) address output pin 12.
EBI_A13	PE6	PE6	PE6					External Bus Interface (EBI) address output pin 13.
EBI_A14	PE7	PE7	PE7					External Bus Interface (EBI) address output pin 14.
EBI_A15	PC8	PC8	PC8					External Bus Interface (EBI) address output pin 15.
EBI_A16	PB0	PB0	PB0					External Bus Interface (EBI) address output pin 16.
EBI_A17	PB1	PB1	PB1					External Bus Interface (EBI) address output pin 17.
EBI_A18	PB2	PB2	PB2					External Bus Interface (EBI) address output pin 18.
EBI_A19	PB3	PB3	PB3					External Bus Interface (EBI) address output pin 19.
EBI_A20	PB4	PB4	PB4					External Bus Interface (EBI) address output pin 20.
EBI_A21	PB5	PB5	PB5					External Bus Interface (EBI) address output pin 21.
EBI_A22	PB6	PB6	PB6					External Bus Interface (EBI) address output pin 22.
EBI_A23	PC0	PC0	PC0					External Bus Interface (EBI) address output pin 23.
EBI_A24	PC1	PC1	PC1					External Bus Interface (EBI) address output pin 24.
EBI_A25	PC2	PC2	PC2					External Bus Interface (EBI) address output pin 25.
EBI_A26	PC4	PC4	PC4					External Bus Interface (EBI) address output pin 26.
EBI_A27	PD2	PD2	PD2					External Bus Interface (EBI) address output pin 27.
EBI_AD00	PE8	PE8	PE8					External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9	PE9	PE9					External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10	PE10	PE10					External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11	PE11	PE11					External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12	PE12	PE12					External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13	PE13	PE13					External Bus Interface (EBI) address and data input / output pin 05.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG15	PA2							LCD segment line 15. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG16	PA3							LCD segment line 16. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG17	PA4							LCD segment line 17. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG19	PA6							LCD segment line 19. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LCD_SEG24	PF6							LCD segment line 24. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG25	PF7							LCD segment line 25. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG26	PF8							LCD segment line 26. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG27	PF9							LCD segment line 27. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG28	PD9							LCD segment line 28. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG29	PD10							LCD segment line 29. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG30	PD11							LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12							LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0							LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1							LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2							LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7							LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8							LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9							LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10							LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11							LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.

5 PCB Layout and Soldering

5.1 Recommended PCB Layout

Figure 5.1. BGA112 PCB Land Pattern

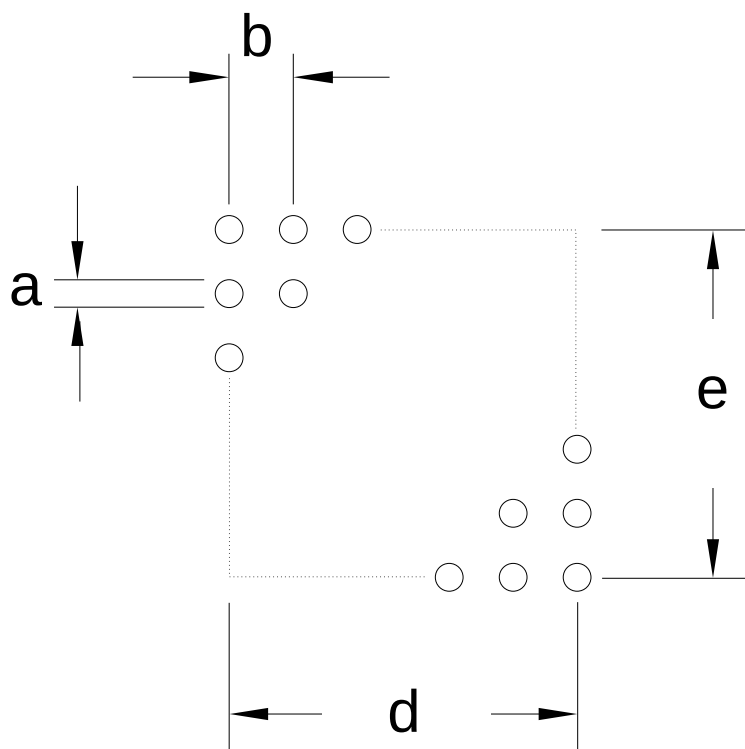
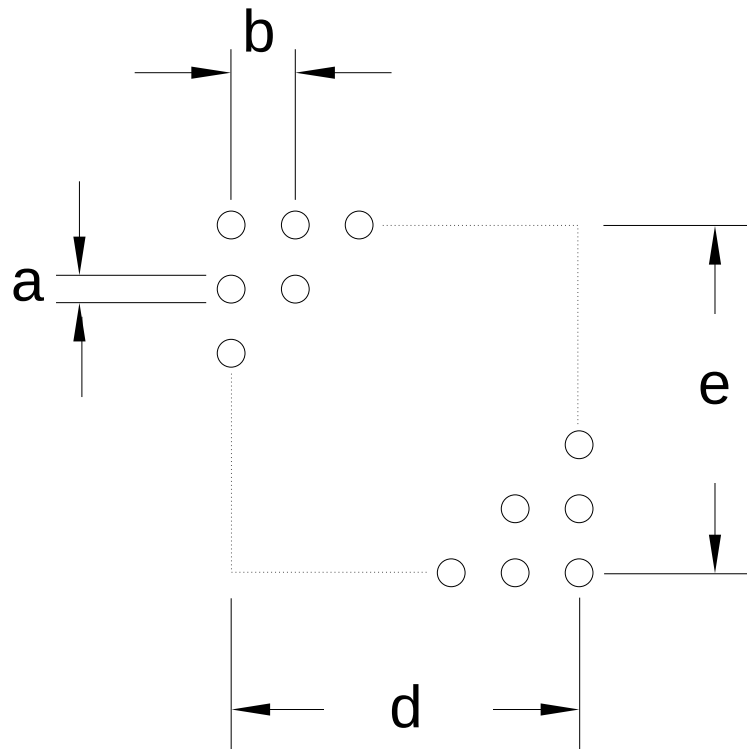
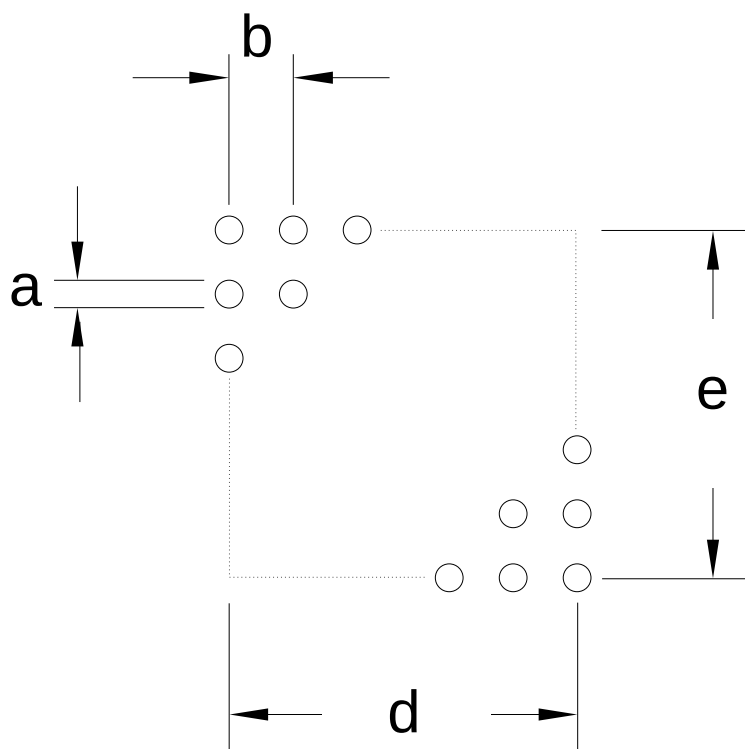


Table 5.1. BGA112 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.35
b	0.80
d	8.00
e	8.00

Figure 5.2. BGA112 PCB Solder Mask**Table 5.2. BGA112 PCB Solder Mask Dimensions (Dimensions in mm)**

Symbol	Dim. (mm)
a	0.48
b	0.80
d	8.00
e	8.00

Figure 5.3. BGA112 PCB Stencil Design**Table 5.3. BGA112 PCB Stencil Design Dimensions (Dimensions in mm)**

Symbol	Dim. (mm)
a	0.33
b	0.80
d	8.00
e	8.00

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Figure 4.3 (p. 67) .

5.2 Soldering Information

The latest IPC/JEDEC J-STD-020 recommendations for Pb-Free reflow soldering should be followed.

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List of Tables

1.1. Ordering Information	2
2.1. Configuration Summary	8
3.1. Absolute Maximum Ratings	10
3.2. General Operating Conditions	10
3.3. Current Consumption	11
3.4. Energy Modes Transitions	13
3.5. Power Management	14
3.6. Flash	15
3.7. GPIO	15
3.8. LFXO	23
3.9. HFXO	23
3.10. LFRCO	24
3.11. HFRCO	24
3.12. AUXHFRCO	27
3.13. ULFRCO	28
3.14. ADC	28
3.15. DAC	38
3.16. OPAMP	39
3.17. ACMP	43
3.18. VCMP	45
3.19. EBI Write Enable Timing	46
3.20. EBI Address Latch Enable Related Output Timing	46
3.21. EBI Read Enable Related Output Timing	47
3.22. EBI Read Enable Related Timing Requirements	48
3.23. EBI Ready/Wait Related Timing Requirements	48
3.24. LCD	49
3.25. I2C Standard-mode (Sm)	50
3.26. I2C Fast-mode (Fm)	50
3.27. I2C Fast-mode Plus (Fm+)	51
3.28. SPI Master Timing	51
3.29. SPI Slave Timing	52
3.30. Digital Peripherals	52
4.1. Device Pinout	54
4.2. Alternate functionality overview	58
4.3. GPIO Pinout	66
5.1. BGA112 PCB Land Pattern Dimensions (Dimensions in mm)	68
5.2. BGA112 PCB Solder Mask Dimensions (Dimensions in mm)	69
5.3. BGA112 PCB Stencil Design Dimensions (Dimensions in mm)	70

List of Equations

3.1. Total ACMP Active Current 43

3.2. VCMP Trigger Level as a Function of Level Setting 45

3.3. Total LCD Current Based on Operational Mode and Internal Boost 49